

MA2B001

Silicon planar type trigger device

Thyristor TRIAC trigger circuit

■ Features

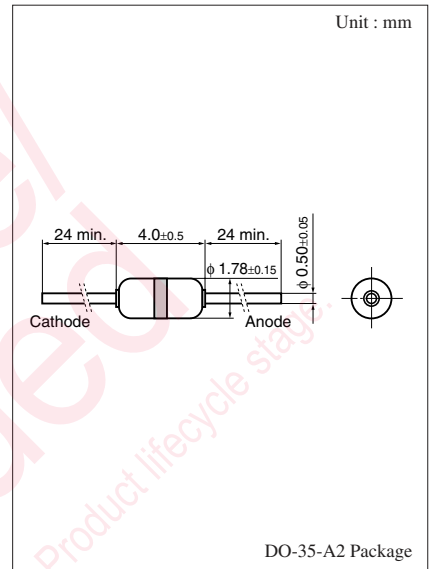
- Satisfactory symmetry of breakover voltage V_{BO}
- Large output voltage V_O and small breakover current I_{BO}

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation (Average)	$P_{D(AV)}$	150	mW
Peak current *1	I_P	2.0	A
Operating ambient temperature *2	T_{opr}	100	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *1: $T_a < 50^\circ\text{C}$, $t = 10 \mu\text{s}$, repetitive frequency 60 Hz

*2: Maximum ambient temperature during operation



■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

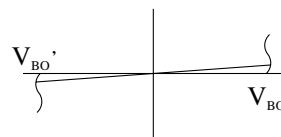
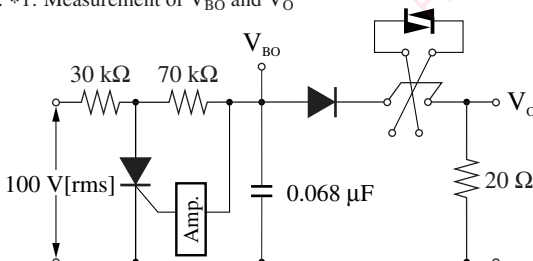
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Breakover voltage *1	V_{BO}	$I = I_{BO}$	28		36	V
Output voltage *1	V_O		4.0	7.0		V
Breakover current	I_{BO}	$V = V_{BO}$			50	μA
Temperature coefficient of breakover voltage	T.C.(V_{BO})			0.1		$\%/^\circ\text{C}$
Breakover voltage deviation *2	ΔV_{BO}				3.5	V

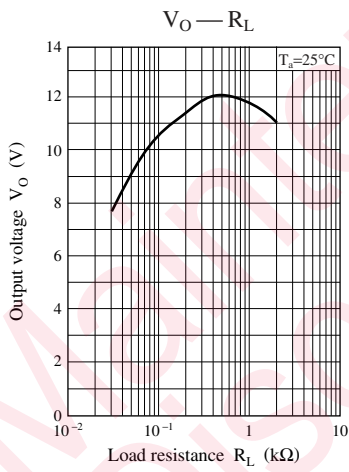
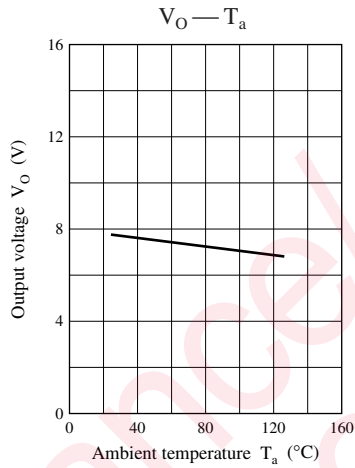
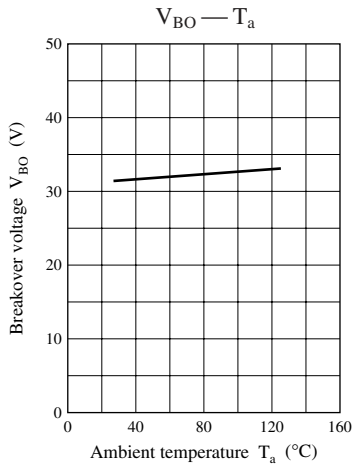
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. Absolute frequency of input and output is 100 MHz.

3. *1: Measurement of V_{BO} and V_O

*2: Symmetry of V_{BO}





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 maintenance type
 planned discontinued type
 discontinued type
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